



DUPONT 7484R

PALLADIUM/SILVER CONDUCTOR

PRODUCT DESCRIPTION

DuPont 7484R Palladium/silver conductor Composition is intended to be applied to ceramic substrates by screen printing and fired in a conveyor furnace in an air atmosphere to form interconnection tracks and pads for component and lead attachment, in hybrid microcircuits and networks.

PRODUCT BENEFITS

- Fine line resolution
- Thin, dense fired films
- Fireable on 30-or 60-minutes 850°C profiles
- Excellent solderability on both Alumina and DuPont QM44 or DuPont 5704 Dielectric
- Excellent aged adhesion on Alumina and on DuPont QM44 or DuPont 5704 Dielectric
- Phthalate, Cadmium, Nickel oxide free*

*Phthalate, Cadmium, and Nickel oxide 'free' as used herein means that cadmium, phthalate and nickel oxide are not intentional ingredients in and are not intentionally added to the referenced product. Trace amounts however may be present.

COMPATIBILITY

When processed under recommended conditions, DuPont 7484R is compatible with most DuPont Resistor systems. Compatible with DuPont 5704 and DuPont QM44 Dielectrics when separately fired. DuPont 7484R is not suitable for cofiring on top of DuPont 5704 and DuPont QM44 Dielectrics.

PROCESSING

Substrates

Properties are based on test on 96% alumina substrates. Substrates of other compositions and from various manufacturers may result in variations in performance properties, as may different lots of substrates, and any subsequent processing of substrates (e.g., laser scribing/drilling) prior to printing.

Printing

Conductor compositions DuPont 7484R should be thoroughly mixed before use. This is best achieved by slow, gentle, hand stirring with a clean, burr-free spatula (flexible plastic) for 30 seconds. Care must be taken to avoid air-bubble entrapment. Printing should be carried out in a clean, well-ventilated area. Note: Optimum printing characteristics of DuPont 7484R are generally achieved in the temperature range 20-23°C. It is therefore important that the material, in its container, is at this temperature prior to printing. A 325-mesh stainless steel screen with a 10-12µm emulsion thickness is normally suggested. 200 mesh screens, can be used but will result in greater fired thickness. Print speeds of up to 25 cm/s may be used.

Fine Line Printing

To achieve the optimum print resolution the following printing parameters are suggested: 325-mesh stainless steel screen with a tension of 30N/cm, emulsion thickness of 12 microns, a print speed of 12.5 cm/s with a 70-80 durometer shore hardness squeegee at an angle of 45°, snap-off of 1.0 mm for a 10 x 8 inch screen.

Drying

Allow prints to level for 5-10 minutes at room temperature, in a clean environment, followed by drying for 10-15 minutes at 150°C in a well ventilated oven or conveyor dryer.

Firing

Fire in a well ventilated belt or conveyor furnace, in air with 30-60 minutes cycle to a peak temperature of 850°C. Care must be taken to ensure that any gases/vapors from other chemicals/materials (e.g., halogenated solvents) do not enter the furnace muffle. It is also essential that the air supply to the furnace is clean, dry and free of contamination.

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Table 1-Typical Fired Properties

Test	Properties	
	On Alumina	On 5704
Fired Thickness line, Pads (µm)	9-13	
Print Resolution (µm lines and space)	≥150	
Resistivity ¹ (mΩ/sq)	15-30	
Solder Acceptance ^{2,3} (%)	>96	
Solder Leach Resistance ^{3,4} (#of dips)	7-9	
Adhesion ^{3,5}		
Initial (N)	>20	>20
Aged (N)	>20	>20
250 µm Al WireBond Adhesion ⁶		
Initial (g)	>500	>500
Aged @150°C, 48 hrs(g)	>500	>500

¹ Normalized to fired thickness of 12 µm

² Percentage of defect free 2 x 2 mm pads, Alpha 611 RMA flux, 5 sec dips in 62Sn/36Pb/2Ag solder at 220°C

³ Firing 1,3 or 5 firing 30 or 60 minute profile

⁴ Number of 10 sec dips on 62Sn/36Pb/2Ag solder at 230°C, 500 µm lines

⁵ See DuPont peel adhesion test procedure

⁶ 250 µm wire bonding, Orthodyne Model 20, heavy Al Bonder, First bond setting: force 500 gms, Time setting 5 (approx. 250 ms), Power setting for first and second bonds 3.0

Table 2-Composition Properties

Test	Properties
Viscosity (Pa.s) Brookfield HBT, UC&SP, 10 RPM, 25°C	150-250
Coverage (cm ² /g) [based on fired film thickness of 11µm]	85-95
Thinner	DuPont 4553

Tables 1 & 2 show anticipated typical physical properties for DuPont 7484R based on specific controlled experiments in our labs and are not intended to represent the product specifications, details of which are available upon request.

STORAGE AND SHELF LIFE

Containers should be stored, tightly sealed, in a clean, stable environment at room temperature (<25°C). Shelf life of material in unopened containers is six months from date of shipment. Some settling of solids may occur and compositions should be thoroughly mixed prior to use.

SAFETY AND HANDLING

For Safety and Handling information pertaining to this product, read the Material Safety Data Sheet (MSDS).



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FOR MORE INFORMATION ON DUPONT 7484R OR OTHER DUPONT MICROCIRCUIT MATERIALS, PLEASE CONTACT YOUR LOCAL REPRESENTATIVE:

Americas

DuPont Microcircuit Materials
14 TW Alexander Drive
Research Triangle Park, NC 27709
USA
Tel +1 800 284 3382 (calls within USA)
Tel +1 919 248 5188 (calls outside USA)

Europe, Middle East & Africa

Du Pont (UK) Ltd
Coldharbour Lane
Bristol BS16 1QD
UK
Tel +44 117 931 3191

Asia

Du Pont Kubushiki Kaisha
MCM Technical Lab
DuPont Electronics Center
KSP R&D B213
2-1, Sakado 3-chom, Takatsu-ku,
Kawasaki-shi, Kanagawa, 213-0012
Japan

Tel +81 44 820 7575

DuPont Taiwan Ltd
45, Hsing-Pont Road
Taoyuan, 330
Taiwan
Tel +886 3 377 3616

DuPont China Holding Company Ltd
Bldg. 11, 399 Keyuan Road
Zhangjiang Hi-Tech Park
Pudong New District
Shanghai 201203
Tel +86 21 6386 6366 ext. 2202

DuPont Korea Inc.
3-5th Floor, Asia tower #726
Yeoksam-dong, Gangnam-gu
Seoul 135-719, Korea
Tel +82 10 6385 5399

E.I. DuPont India Private Limited
7th Floor, Tower C, DLF Cyber Greens
Sector-25A, DLF City, Phase-III
Gurgaon 122 002 Haryana, India
Tel +91 124 409 1818

Du Pont Company (Singapore) Pte Ltd
1 HarbourFront Place, #11-01
HarbourFront Tower One
Singapore 098633
Tel +65 6586 3022

mcm.dupont.com

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CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 K-28861 (11/14)